	BLE STAN				Storage				
	Operating Temperature Range 2 Voltage Current				Storage Temperatur	e Range	-10 °C to 60 °C $^{(2)}$		(2)
Rating			Power Contact : 200 V AC		Storage Hu	orage Humidity Range Relative humidit		% max	
			Signal Contact : 0.5 A Power Contact : 3.0A			perating Humidity Range (Not dewed)			
			SPEC	IFICATIO	ONS				
IT	EM		TEST METHOD			REQU	IREMENTS	QT	A
CONSTRU	JCTION							I	1
General Examination		Visually and by measuring instrument.			Accord	According to drawing.			>
Marking		Confirmed	-					×	>
ELECTRIC CHARAC									
Contact Resistance		100 mA(DC or 1000Hz)			-	Signal Contact : $70m \Omega$ MAX. Power Contact : $20m \Omega$ MAX.			-
Insulation Resistance		Signal Contact : 100 V DC. Power Contact : 250 V DC			-	Signal Contact : 100 M Ω MIN. Power Contact : 1000 M Ω MIN.			-
Voltage Proof		Signal Contact : 150 V AC for 1 min.			No floo	No flashover or breakdown.			>
		Power Contact : 600 V AC for 1 min.							_
	CAL CHAR								
Insertion and		Measured by applicable connector.				Insertion Force: 54 N MAX.			-
Withdrawal Forces Mechanical Operation		100 times insertions and extractions.				Withdrawal Force: 6 N MIN.			-
Mechanical Operation		100 times insertions and extractions.			S	 Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX. No damage, crack and looseness of parts. 			
Vibration		Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles			① No	 No electrical discontinuity of 1 μs. No damage, crack and looseness of parts. 			1 -
Shock		for 3 axial directions. 490 m/s ² , duration of pulse 11 ms						×	-
			for 3 both axial directions.						
	MENTAL C	-						-	
Damp Heat (Steady state)		Exposed at 40±2 °C, 90 ∼ 95 %, 96 h.			S	① Contact Resistance: Signal Contact : 80m Ω MAX.			-
Rapid Change of Temperature		Temperature $-55 \rightarrow +85 \circ C$ Time $30 \rightarrow 30 \text{ min.}$ under 5 surplase			-	Power Contact : 30m Ω MAX. ② Insulation Resistance: Signal Contact : 100 MΩ MIN.			-
					~				
		under 5 cycles. (Relocation time to chamber : within 2~3 MIN)			F	Power Contact	:: 1000 MΩ MIN.		
Cold		Exposed at -55°C, 96 h			1 Cor	 ③ No damage, crack and looseness of parts. ① Contact Resistance: Signal Contact : 80m Ω MAX. 			-
Dry Heat		Exposed at 105°C, 96 h			P	Power Contact : 30m Ω MAX. ② No damage, crack and looseness of parts.			-
Sulfur Dioxide		Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h.			n. ① No	 No defect such as corrosion which impairs 			- 1
		(Test standard: IEC 68)			the ② Cor S	 the function of connector. (2) Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX. 			
Resistance to		1)Reflow soldering :				No deformation of case of excessive			-
Soldering Heat		Peak TMP : 260°CMAX Reflow TMP: 220°CMIN for 60sec			loosen	looseness of the terminal.			
			g irons : 360°C MAX. for 5	sec.					
Solderability			t solder temperature for immersion duration, 3 se	ec.		um of 95 % of	ng of solder shall cover a the surface being	×	-
COUN	т р		N OF REVISIONS		ESIGNED		CHECKED		TE
2 2					IS. 00N0				
			-F-00002057		13. UUNU		HS. OKAWA	17.02.0 14.07.2	
REMARKS ⁽¹⁾ Include temperature rise caused by current-carrying. ⁽²⁾ "STORAGE" means a long-term storage state for the unused product before assembly to PCB.						KN. SHIBUYA	14.07.2		
Union official and the second second						DESIGNED	TS. OONO	14.07.2	
Unless otherwise specified, refer to IEC 60512.						DRAWN TS. 00N0			7.2
Note QT:Q		st AT:Assurance Test X:Applicable Test						ELC-353542-00-00	
HRS	-	SPECIFICATION SHEET HIROSE ELECTRIC CO., LTD.					X23-120P-0. 5SV15	~	1/
					DDE NO.	DE NO. CL573-3006-4-00			17